

5 Board Layout

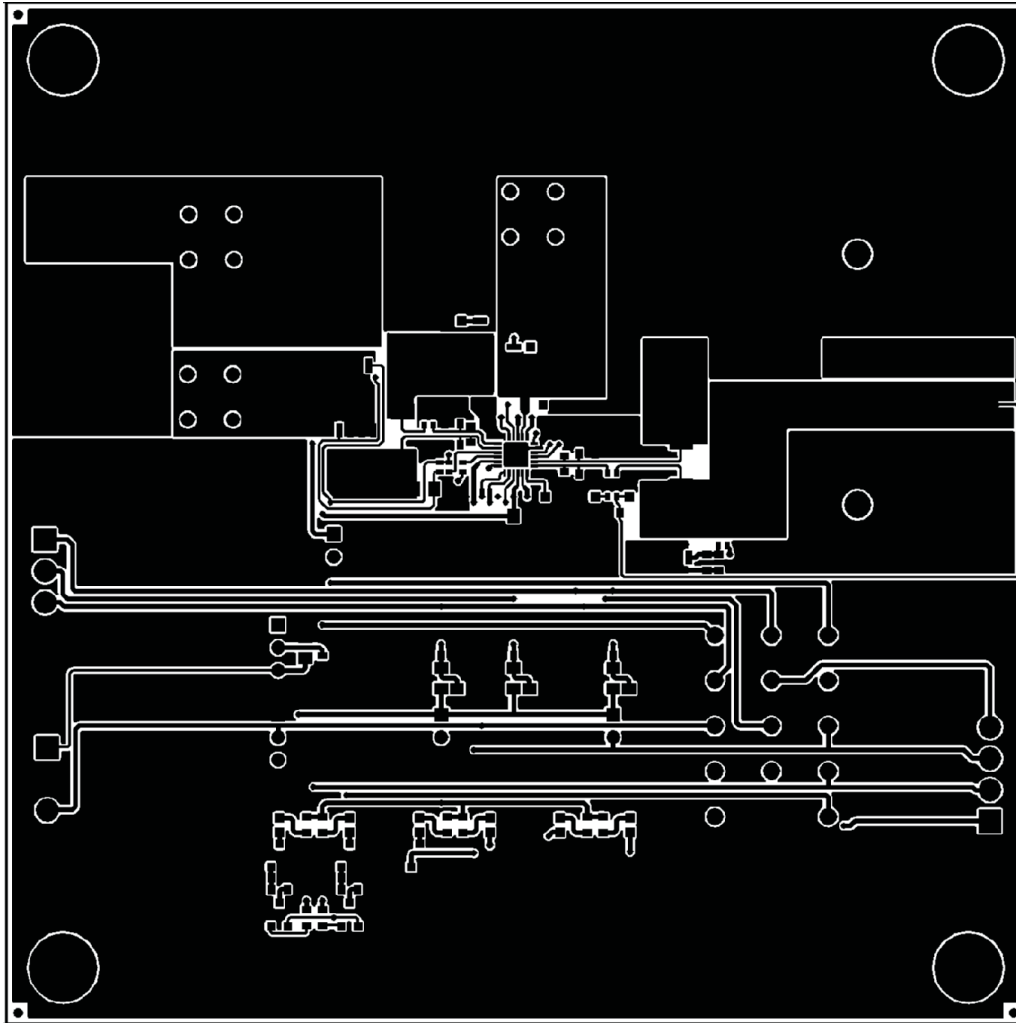


Figure 2. Top Layer

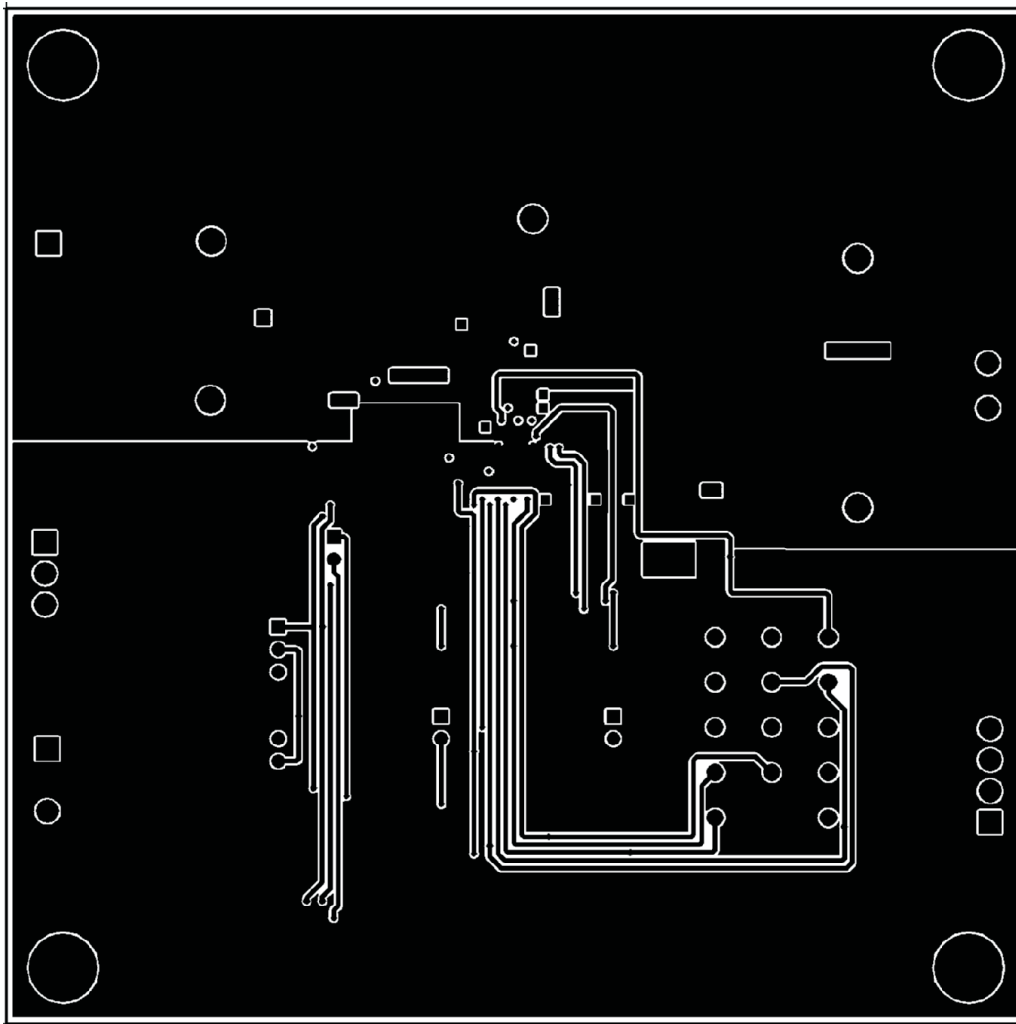


Figure 3. 2nd Layer

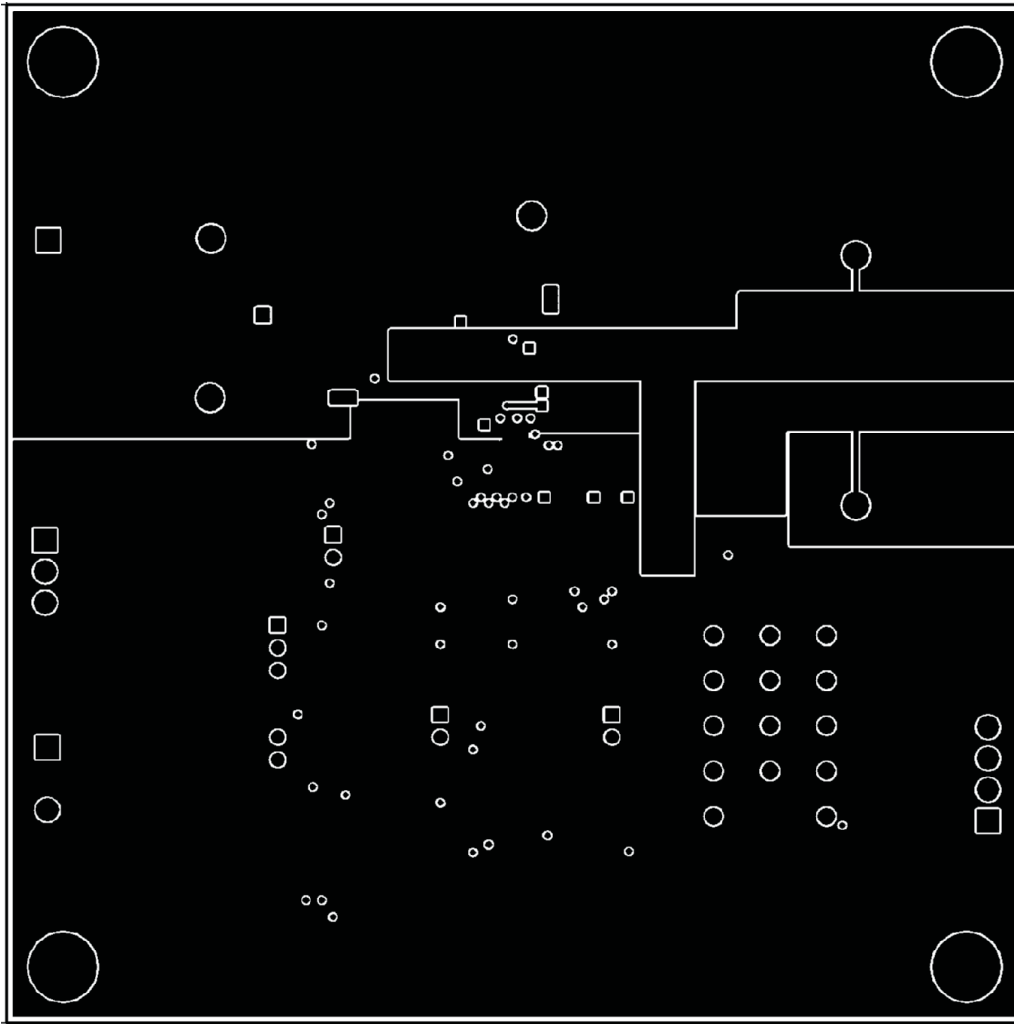


Figure 4. 3rd Layer

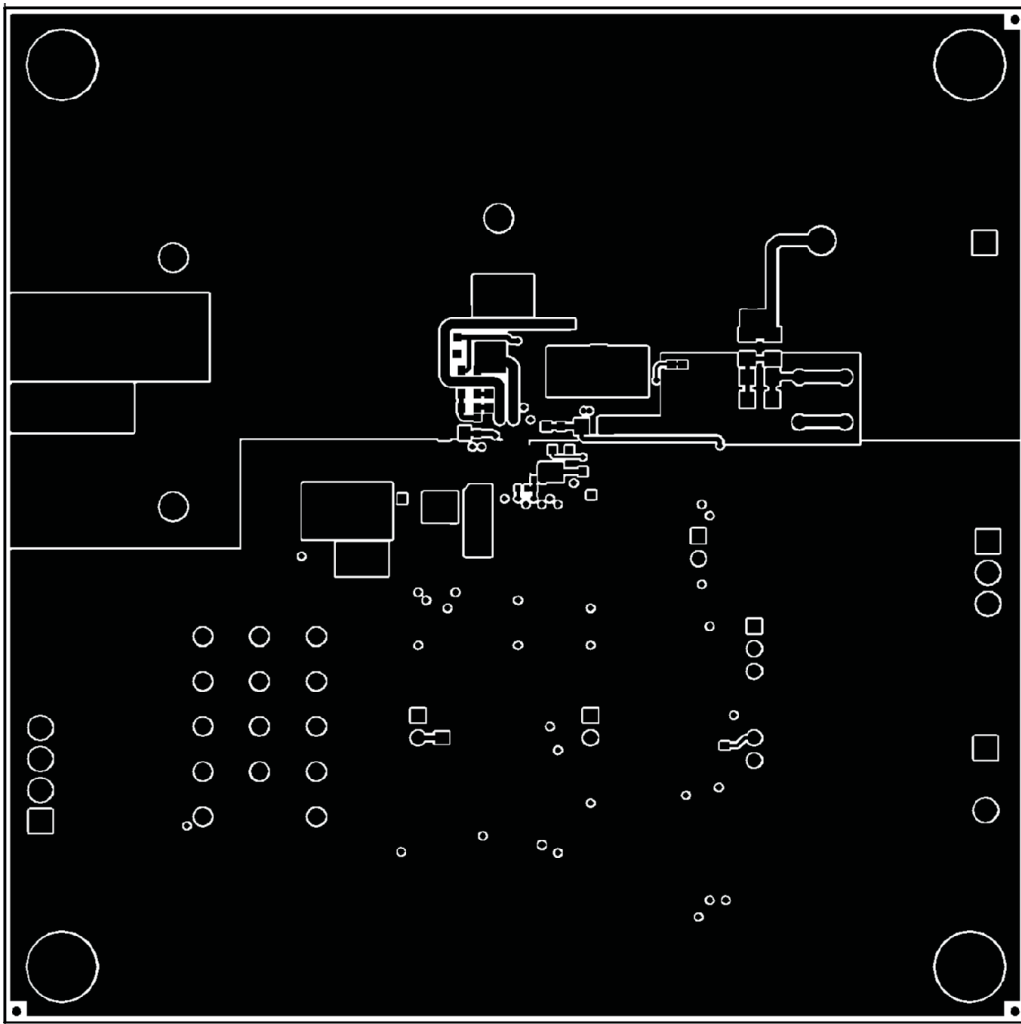


Figure 5. Bottom Layer

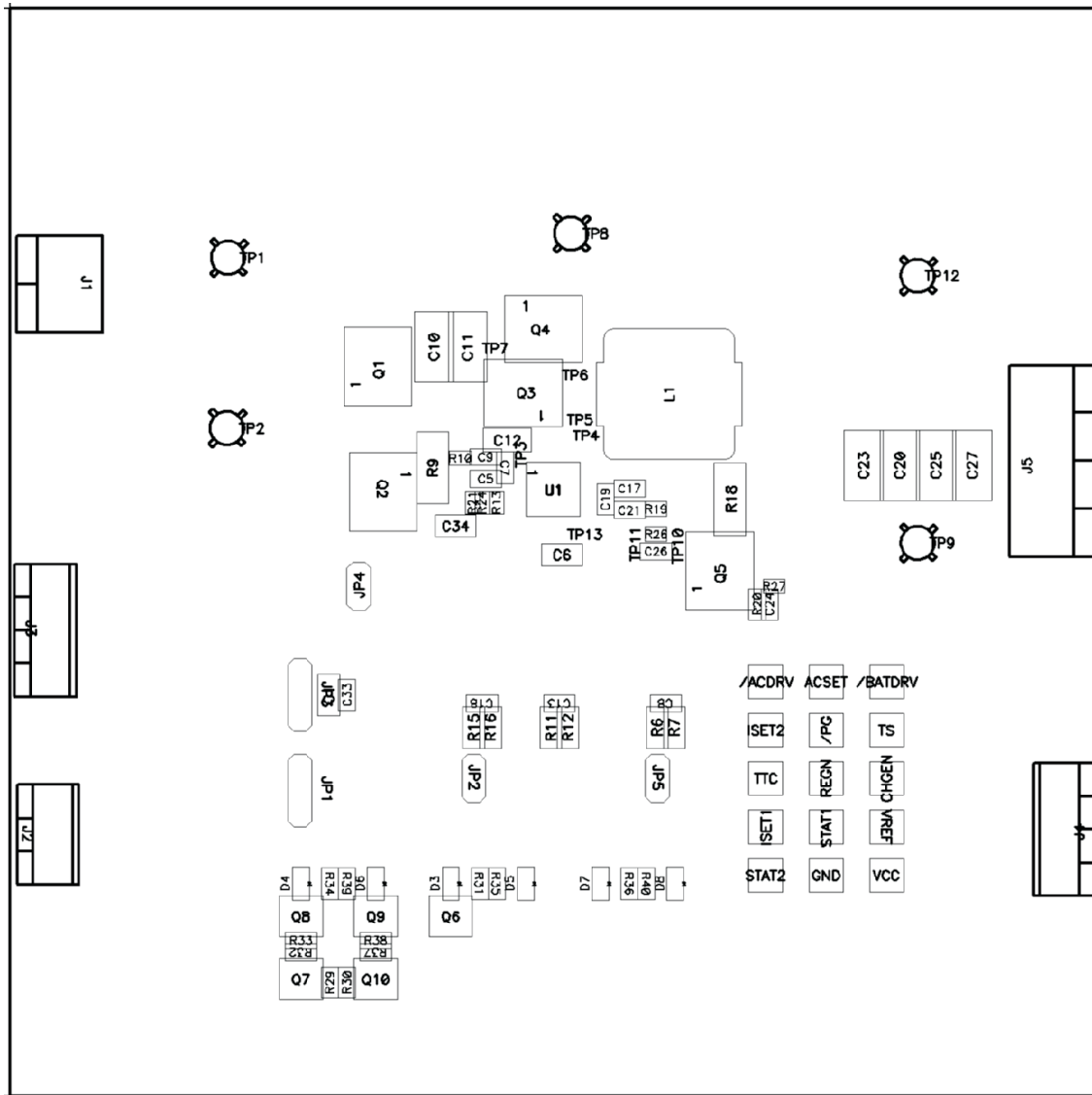


Figure 6. Top Assembly

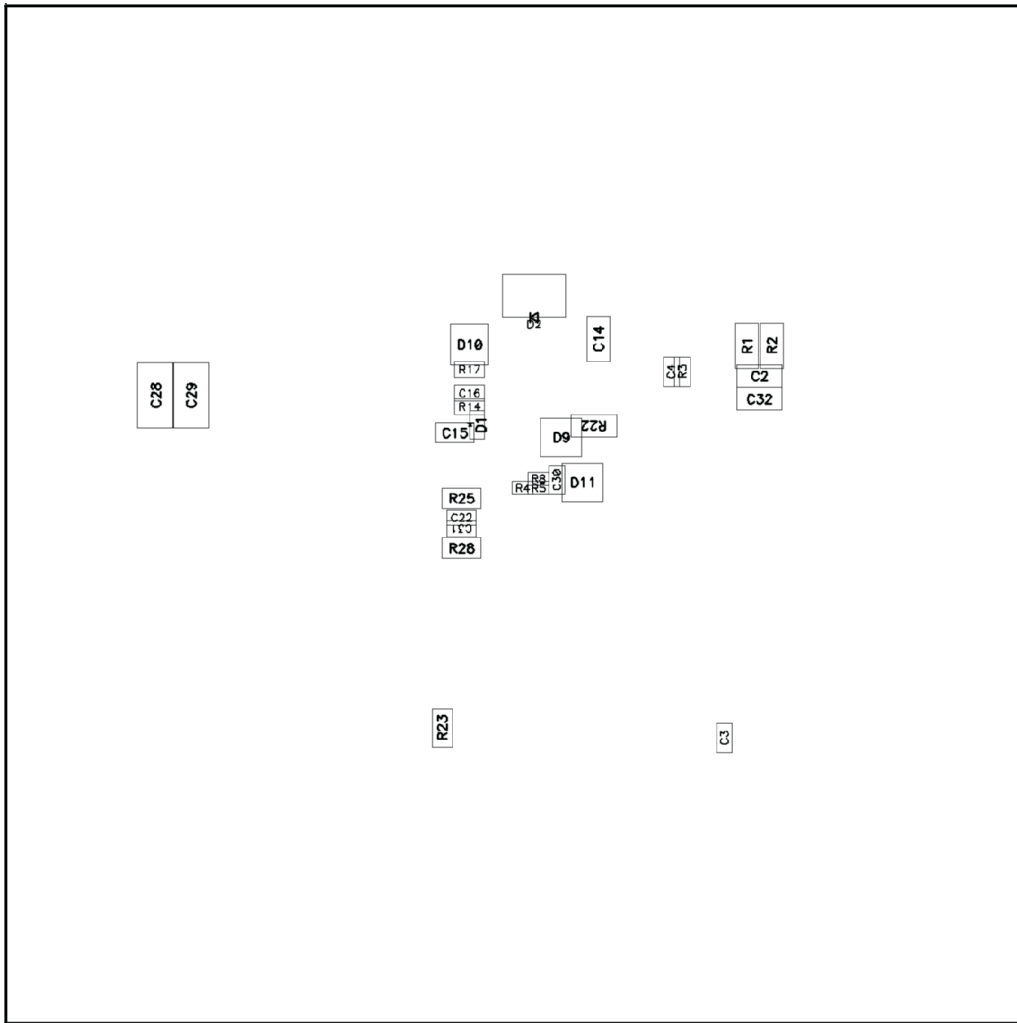


Figure 7. Bottom Assembly

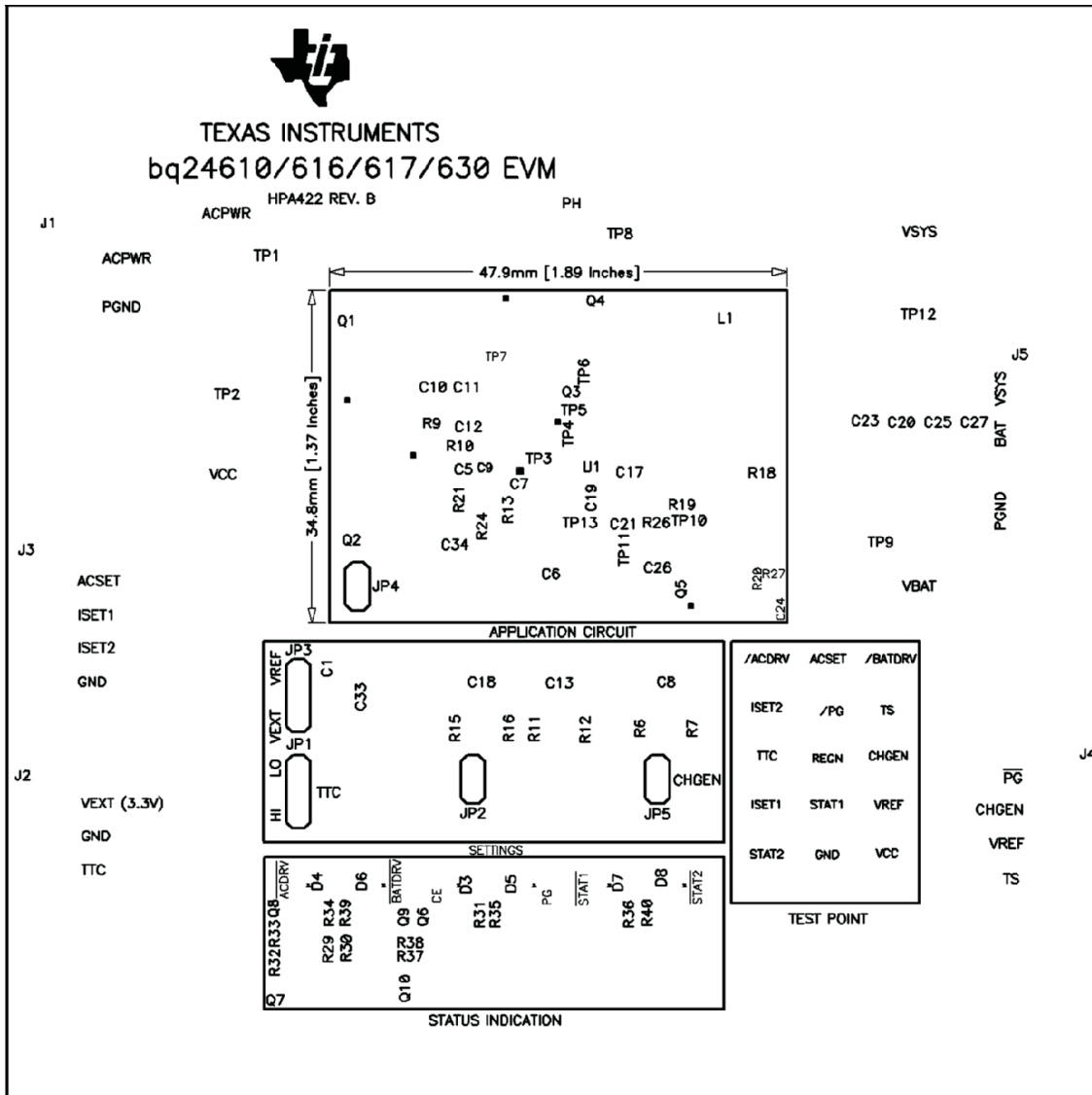


Figure 8. Top Silkscreen

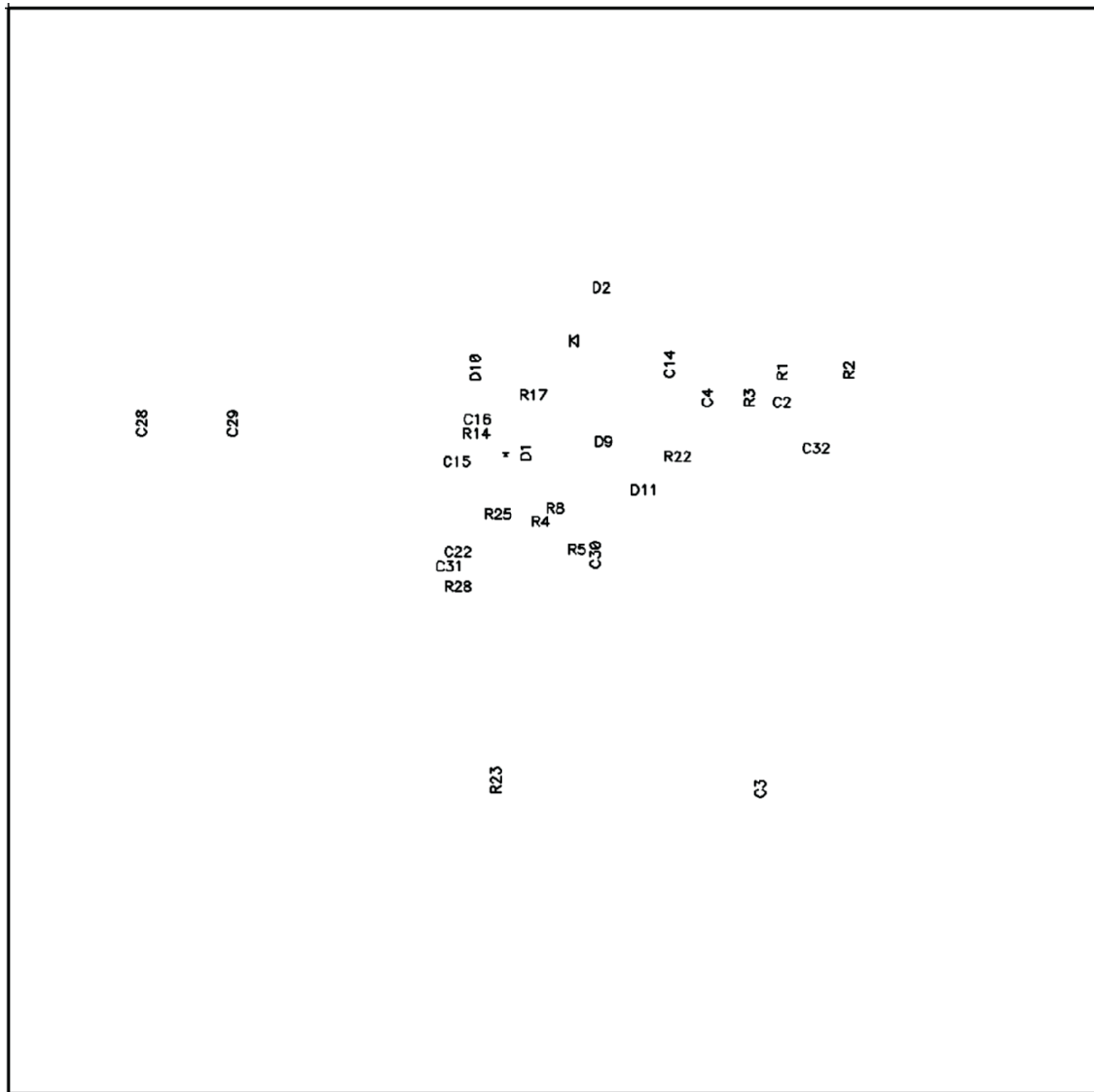


Figure 9. Bottom Silkscreen

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